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Abstract

Method for producing a multichip module and multichip module

The present invention provides a method for producing a multichip module having the following steps: (a) application of at least one contact elevation (11) onto a substrate (10); (b) application and patterning of a rewiring device (12) onto the substrate (10) and the at least one contact elevation (11) with provision of a contact device (13) on the at least one contact elevation (11); (c) application of a semiconductor chip (15) onto the substrate (10) with electrical contact-connection of the rewiring device (12); (d) application of an encapsulating device (16) that is not electrically conductive onto the semiconductor chip (15), the substrate (10), the rewiring device (12) and the at least one contact elevation (11), the contact device (13) on the at least one contact elevation (11) at least touching a first surface (16') of the encapsulating device (16); and (e) repetition at least once of at least steps (a) and (b), the first surface (16') of the encapsulating device (16) serving as a substrate and the correspondingly produced rewiring device (12) making electrical contact with the contact device (13) of the at least one contact elevation (11) of the underlying plane. The present invention likewise provides a multichip module.

Figure 12

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